

Optimal geometry selection for Hall sensors integrated in CMOS technological process

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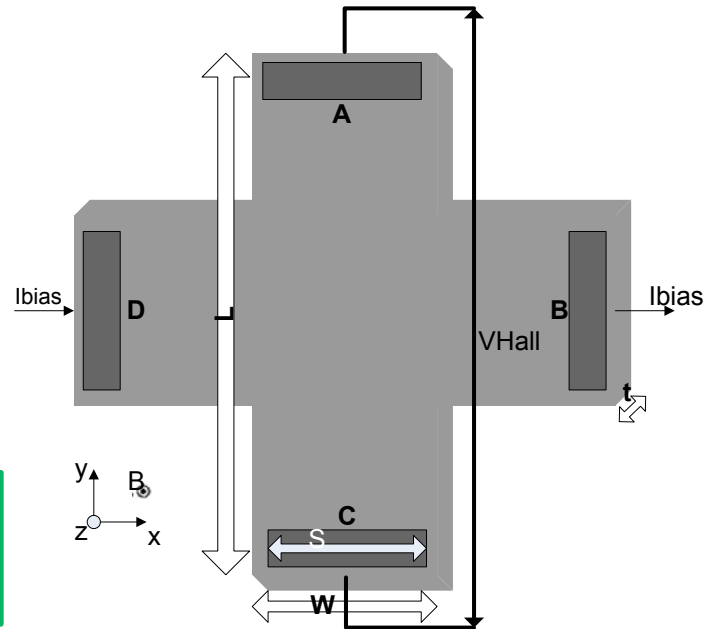
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Summary

- Different Hall cells have been integrated in regular bulk CMOS technology (XFAB CMOS XH 0.35 μm) and analyzed in terms of their specific parameters.
- Geometry plays an important role in Hall cells performance. The focus of this work is on Basic and L Hall cells.
- Accurate single and multi-phase offset numerical estimations have been provided for the Basic Hall cell.
- The most important parameters of the Hall cells, based on regular bulk structure, are also evaluated through three-dimensional physical simulations.

Hall Effect Sensors



$$(1) \quad V_{HALL} = S_A B$$

$$S_A = \frac{Gr_H}{nqt} I_{bias} \quad (2)$$

- low-power applications
- current sensing
- position detection & contactless switching

Hall Cells Design Selection

- Different 3D Hall sensors were integrated in regular bulk CMOS technology.
- They are all symmetrical and orthogonal structures.
- The geometry plays an important role in the sensors performance.

$$G \cong 1 - \frac{16}{\pi^2} \exp\left(-\frac{\pi L}{2W}\right) \left[1 - \frac{8}{9} \exp\left(-\frac{\pi L}{2W}\right)\right] \left(1 - \frac{\theta_H^2}{3}\right) \quad (3)$$

valid if $0.85 \leq L/W < \infty$ and $0 \leq \theta_H \leq 0.45$

Hall Effect Sensors Measurements

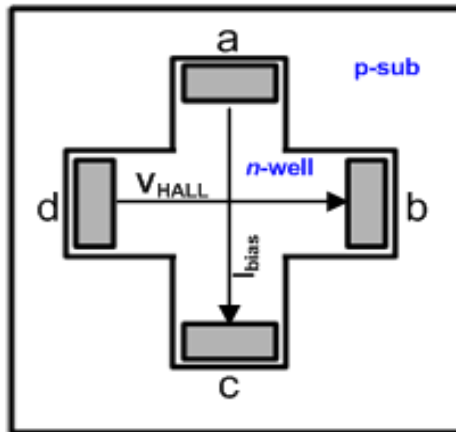
- Measurements results on nine different Hall Effect sensors in regular bulk CMOS

Objectives: offset @ T=300 K < ±30 μT & offset drift < ±0.3 μT/°C

Geometry Type	Basic	Low-doped	L	XL	45 Deg	Narrow Contacts	Borderless	Square	Optimum
Integrated Shape (CMOS 0.35 μm)									
R_{θ} (kΩ) @ T=300 K, B=0 T	2.3	5.6	2.2	2.2	2.1	2.5	1.3	4.9	1.5
S_A (V/T) @ $I_{bias}=1$ mA	0.0807	0.3392	0.0804	0.0806	0.0807	0.0822	0.0325	0.0884	0.0635
Offset drift (μT/°C) (4-phase current spinning)	0.409	0.067	0.264	0.039	0.373	0.344	0.526	0.082	0.328
L, W (μm) of the Active Area (N-well)	L=21.6 W=11.8	L=21.6 W=11.8	L=32.4 W=17.8	L=43.2 W=22.6	L=21.64 W=11.8	L=21.6 W=9.5	L=50 W=50	L=20 W=20	L=54 W=54
L/W	1.83	1.83	1.82	1.91	1.83	2.27	1	1	1
s (μm) for Sensing Contacts	11	11	16	20.7	11	1.5	2.3	2.3	5.4
Geometrical Correction Factor (G)	0.913	0.913	0.912	0.924	0.913	0.87	0.76	0.73	0.74

Single Phase and Residual Offset

- Cell polarization and the corresponding phases



Greek-cross cell polarization

Phases	I_{bias}	V_{HALL}
Phase 1	a to c	b to d
Phase 2	d to b	a to c
Phase 3	c to a	d to b
Phase 4	b to d	c to a

- Single phase offset and residual offset

$$V_{\text{out}} = V_{\text{HALL}}(B) + V_{\text{offset}} \quad (4)$$

$$\text{Offset}_{\text{residual (4 phase)}} = \frac{V_{P1} - V_{P2} + V_{P3} - V_{P4}}{4} \quad (5)$$

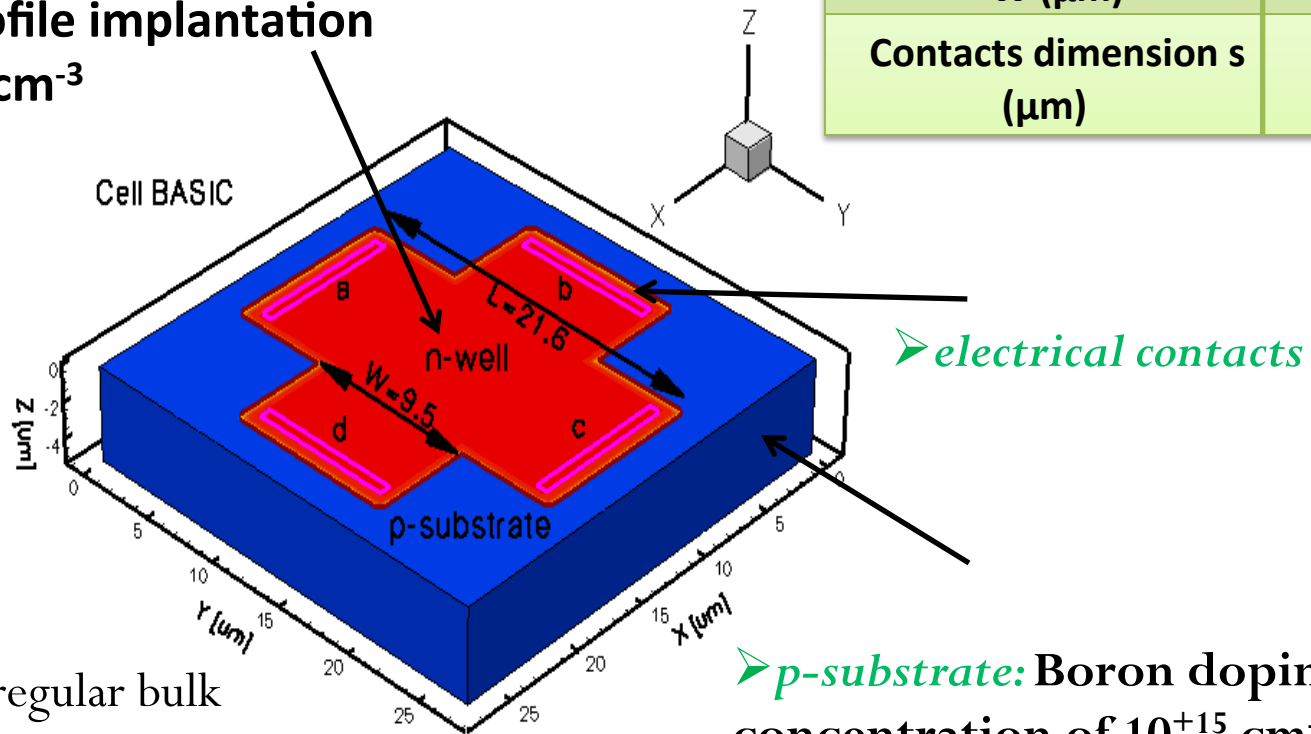
The 3D Simulation of regular bulk Hall Cells

➤ The Basic Hall structure follows the XFAB XH 0.35 fabrication process.

➤ **active n-well region:** Arsenic doping

- ✓ Gauss profile implantation
- ✓ $1.5 \cdot 10^{17} \text{ cm}^{-3}$

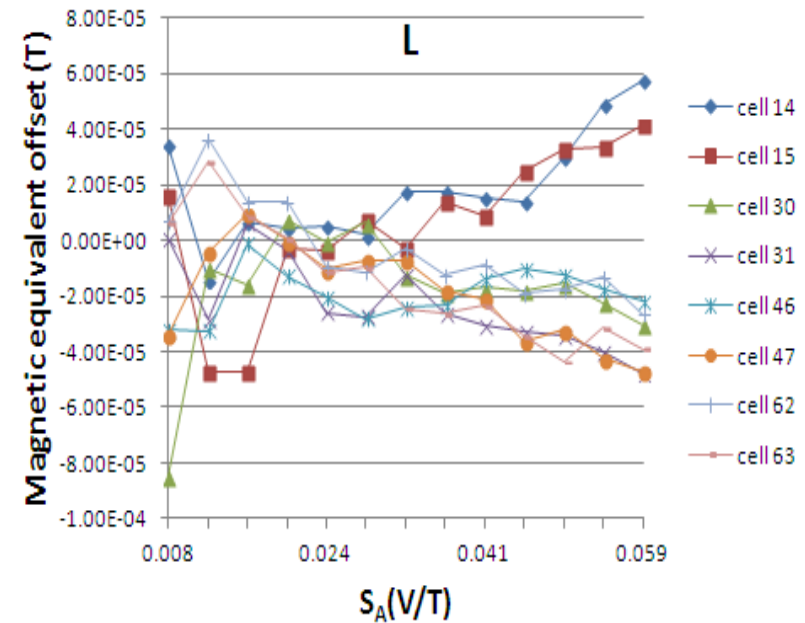
Parameter	Value
L (μm)	21.6
W (μm)	9.5
Contacts dimension s (μm)	8.8



The 3D model of regular bulk Basic Hall cell

Hall cells magnetic equivalent 2- and 4-phase offset

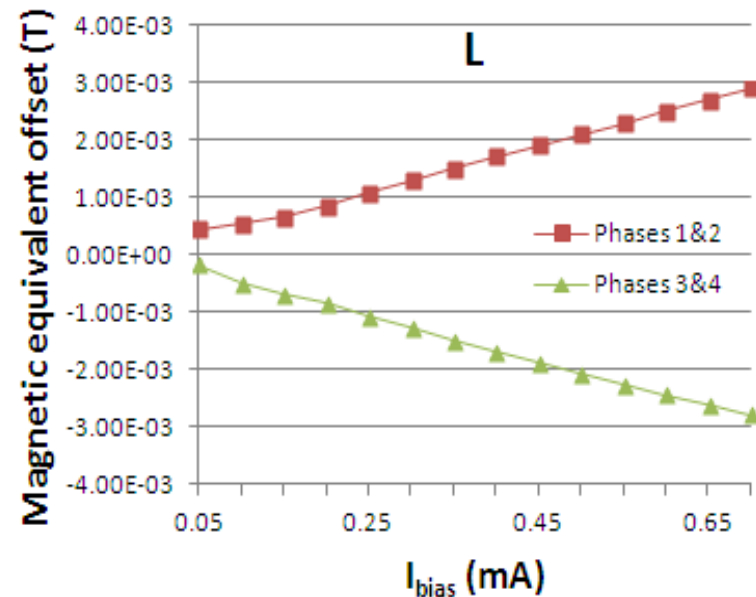
- DC setup was used again
- Each cell was tested 8 times on the chip
- Lowest offset level on XL cell



- DC setup was used

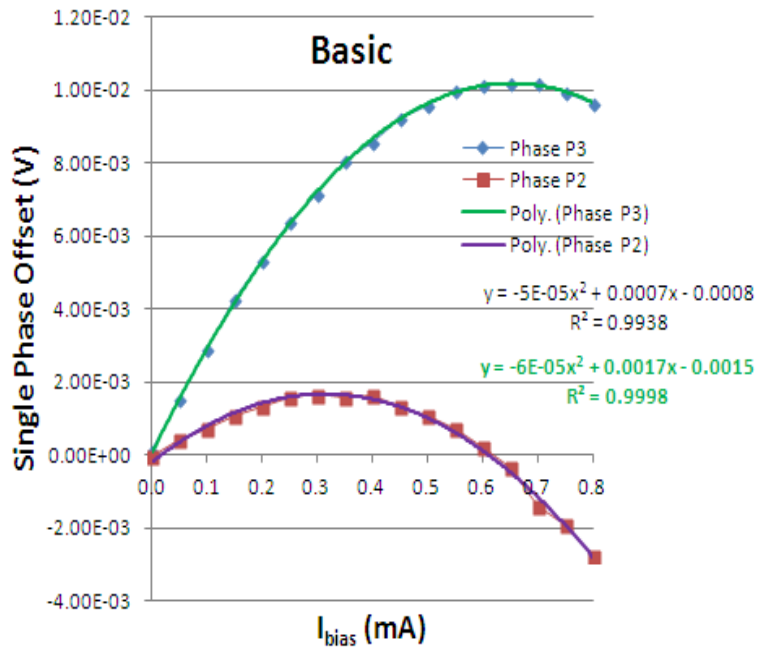
$$B_{offset, 1\&2} = \frac{1}{100} \frac{V_{P1} + V_{P2}}{2} \frac{1}{S_A} \quad (6)$$

$$B_{offset, 3\&4} = \frac{1}{100} \frac{V_{P3} + V_{P4}}{2} \frac{1}{S_A} \quad (7)$$



Offset measurements (I)

- Single phase offset was measured by an automated measurements setup
- Quadratic behaviour of the single phase offset with the biasing current was proven

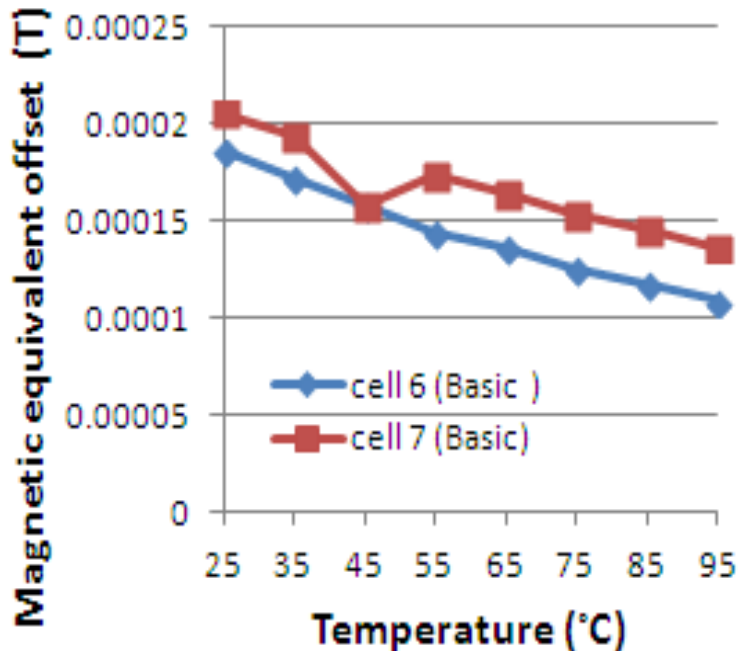


Measured single phase offset (V)
versus I_{bias} for Basic Hall cell

Coefficients	Basic Cell	
	Phase P2	Phase P3
a (V/mA)	0.0007	0.00017
b(V/m ² A ²)	-5E-5	-6E-5
R ²	0.9938	0.9998

Offset measurements (II)

- Magnetic equivalent offset temperature variation was investigated
- Measured for Basic Hall cell in regular bulk CMOS



Measured magnetic equivalent offset (T) versus the temperature, for the Basic Hall cell

- Offset temperature drift is important.
- Temperatures from 25 to 95 °C were considered, by the means of a Temptronic oven.
- The same Basic cell was tested twice.

Averaged Offset Drift
for Basic Hall cell:
0.409 $\mu\text{T}/^\circ\text{C}$

Conclusions

- This work was intended to analyze the behaviour of Hall cells in regular bulk CMOS fabrication process.
- Different offset numerical estimations (single phase, multi phase offset voltage, residual offset, magnetic equivalent offset, post-encapsulation offset) were investigated.
- Special attention was given to prove the quadratic behaviour of the offset with the biasing current.
- The variation of the magnetic equivalent offset with the temperature was also performed for the CMOS Basic Hall cell, for a 25 to 95 °C range.

References (selective list)

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Thank you for your kind attention!

